

BPT-HP232X-TRB

產品承認書

Product Approval Sheet

一.基本內容(INFORMATION)

客戶名稱(Customer Name):

產品型號(Product Number): BPT-HP232X-TRB

料號信息(PN Information):

1199011100.(,				
安氏虾塘	參數要求				
客戶料號	I _{C(ON)(mA)}	λ d (nm)	λ p(nm)	電壓 (V)	CRI (Ra)
	4.976~14.859	500~1000	940		

二.供應商確認欄(SUPPLIER)

核准(Approved/Date)	審核(Check/Date)	製作(Prepared/Date)
張孝嚴 2016-1-25	張喜光 2016-1-25	熊燦芬 2016/1/25

三.客戶批准欄(CUSTOMER)

產品承認書批准處埋:□同意	□ 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	
核准(Approved/Date)	審核(Check/Date)	研發/工程(R&D Dept/Date)

說明:請將已簽副本回覆我司

Please return to us one copy "PRODUCT ACKNOWLEDGEMENT SHEET" with your approved signatures!

佰鴻工業股份有限公司

BRIGHT LED ELECTRONICS CORP.

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Taipei, Taiwan, R. O. C. Tel: 886-2-29591090

Fax: 886-2-29547006/29558809

www.brtled.com.

Ver1.0 Page: 0 of 8



BPT-HP232X-TRB

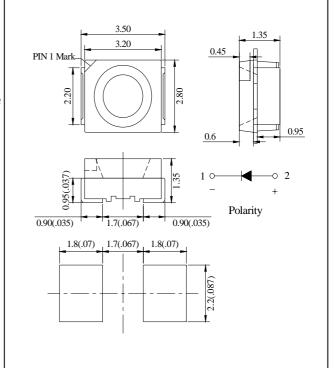
Features:

- High radiant power and high radiant intensity.
- 2. Lens Appearance: Water clear.
- 3. 3.5*2.8*1.35mm standard package.
- 4. Suitable for all SMT assembly methods.
- 5. Compatible with infrared and vapor phase reflow solder process.
- 6. Compatible with automatic placement equipment.
- 7. This product doesn't contain restriction Substance, comply ROHS standard.

Applications:

- 1. Lighting
- 2. Automotive lighting.
- 3. Backlighting: LCDs
- Status indicators: Consumer & industrial electronics.
- 5. General use.

PackageDimensions:



NOTES:

- 1.All dimensions are in millimeters.
- 2.Tolerance is ±0.10mm unless otherwise

■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	75	mW
Emitter-Collector Breakdown Voltage	BV_CEO	30	
Emitter-Collector Breakdown Voltage	BV _{ECO}	5	V
Operating Temperature	Topr	-40°℃~80°℃	-
Storage Temperature	Tstg	-40°C~100°C	-
Soldering Temperature	Tsol	See Page 6	-

Note: IFP is pulse of 1/10 duty at 1KHz



■ Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Spectrum Sensitivity	λd	I _F =50mA	500	-	1000	nm
Short Circuit Current	λр	I _F =50mA	-	940	-	nm
Collector Light Current	$I_{C(ON)}$	V _{CE} =5V, λp=940nm, H=1.0mw/cm ²	4.976	7.165	-	mA
Collector Dark Current	I_{CEO}	V _{CE} =20V	-	-	100	nA
Rise/Fall Time	Tr/Tf	V_{CE} =5V, Ic=1mA, R_L =1 $K\Omega$		15/15	-	us
Viewing Angle	2θ _{1/2}	I _F =50mA	-	120	-	deg

Typical Electro-Optical Characteristics Curves.

Fig.1 Collector current vs Collector emitter voltage

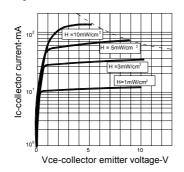


Fig.2 Ambient temperature vs.Collector Dissipantion

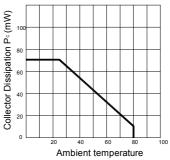


Fig.3 Dark current vs Free-air temperature

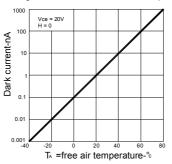
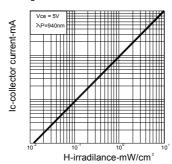
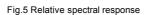
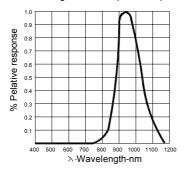


Fig.4 Collector current vs Irradlance



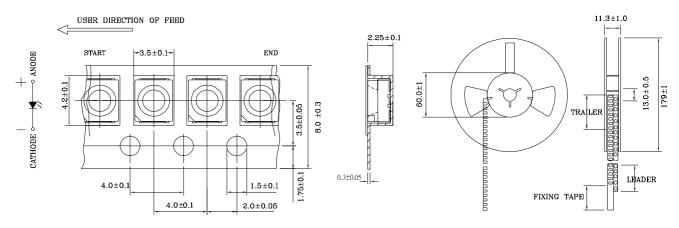






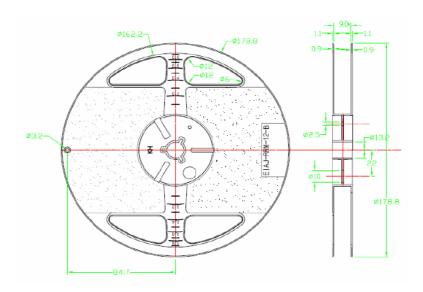
Tapping and packaging specifications(Units: mm)

■ Dimensions Of Reel



NOTE:2000 PCS PER REEL

Dimensions Of Reel



Tolerance: ± 0.1

Unit: mm

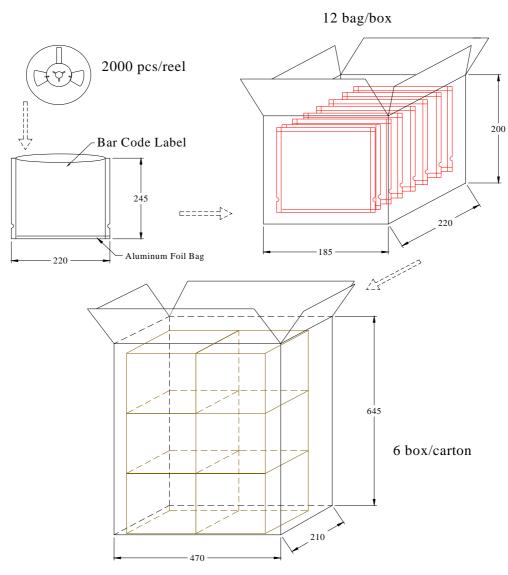
(1) Quantity: 2000PCS /Reel

(2) Adhesion strength of cover tape to be $0.1 \sim 0.7N$ when the cover tape is turned off from the carrier tape.

Ver1.0 Page: 3 of 9



Package Method:(unit:mm)



Intensity Bin Limits (At 50 mA)

Collector Light Current Bin Limits($V_{CE}=5V$, H=1.0mw/cm 2 , λ p=940nm)

BIN CODE	$I_{C(ON)}(mA)$		
BIN CODE	Min	Max	
Р	4.976	7.165	
Q	7.165	10.319	
R	10.319	14.859	

Tolerance for each Bin limit is ± 15 %

● BIN : <u>x</u>

Collector Light Current Bin Code



Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	I _F =50mA Ta=Under room temperature Test time=1,000hrs	0/20
Endurance	High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	Ta=+65°C±5°C RH=90%-95% Test time=240hrs	0/20
Test	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+85°C±5°C Test time=1,000hrs	0/20
	Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-35°C±5°C Test time=1,000hrs	0/20
	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	-35°C ~ $+25$ °C ~ $+85$ °C ~ $+25$ °C 60min 20min 60min 20min Test Time=5cycle	0/20
Environmental Test	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	-35°C±5°C ~+85°C±5°C 20min 20min Test Time=10cycle	0/20
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS-C-7021 :A-1	Preheating: 140℃-160℃,within 2 minutes. Operation heating: 260℃(Max.), within 10seconds. (Max.)	0/20

Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	$V_{F}(V)$	I _F =50mA	Over U ¹ x1.2
Reverse current	$I_R(uA)$	V _R =5V	Over U ¹ x2
Luminous intensity	lv (mcd)	I _F =50mA	Below S ¹ X0.5

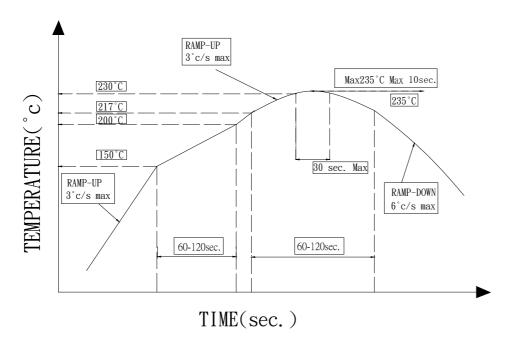
Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. After each test, remove test pieces, wait for 2 hours and test pieces have returned to ambient temperature, then take next measurement.

Ver1.0 Page: 5 of 9



●IR-Reflow Soldering



- Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering.
- 2. Avoid rapid cooling or any excess vibration during temperature ramp-down process
- Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

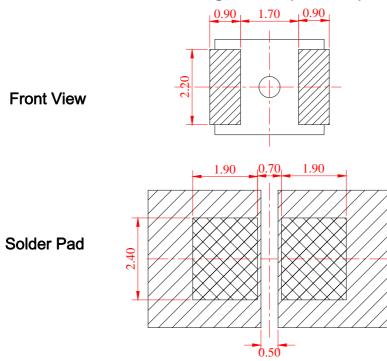
IRON Soldering

300°C Within 3 sec, one time only.

Ver1.0 Page: 6 of 9



Recommended Soldering Pattern (Unit:mm)



Handling:

Care must be taken not to damage LED's epoxy resin while exposing to high temperature or contact LED's epoxy resin with hard or sharp objects, such as metal hook, tweezer or sand blasting.



Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is slfter and flexible. Although its characteristic

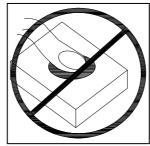
Significantly reduces ghermal stress, it is more susceptible tl damage by extermal mechanical rorce. As a result, special handling precautions need tl be observed during assembly using silicong encapsulated

LED priducts. Failure to cimply might lead ti damage and premature failure of ghe LED.

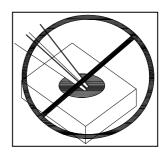
- 1. Handle the component along the side surfaces by using forceps Ir appropriate tools.(pic.1)
- 2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry. (pic.2,pic.3)
- 3. Do not stack together assembled PCBs congaining exposed LEDs. Impact may scratch the silicone lens or Damage the internal circuitry. (pic.4)
- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. (pic.5)
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface duringpickup. (pic.5)
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machie to insure precise pickup and avoid damage during production. (pic.5)



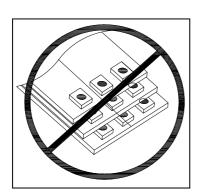
Pic.1



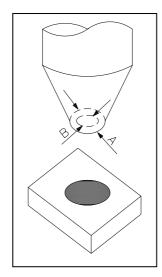
Pic.2



Pic.3



Pic.4



Pic.5



Notes for designing:

Current limiting resistor must be used in the circuit to drive BRIGHT LEDs within the rated figures and not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF cycles. When using pulse driving, the average current must be within the rated figures. And the circuit should be designed to avoid reverse voltage when turning off the BRIGHT LEDs.

Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

Temperature : 5° C - 30° C (41° F) Humidity : RH 60% Max.

After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:

Completed within 168 hours.

Stored at less than 30% RH.

Devices require baking before mounting, if:

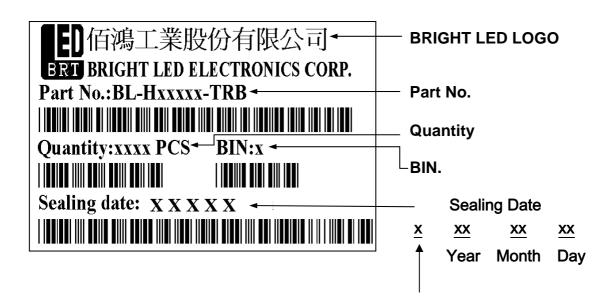
(2) a or (2) b is not met.

If baking is required, devices must be baked under below conditions:

48 hours at 60°C±3°C.

Package and Label of Products:

Package: Products are packed in one bag of 2000 pcs (one taping reel) and a label is attached to each bag. Label:



Manufacture Location

Ver1.0 Page: 9 of 9

单击下面可查看定价,库存,交付和生命周期等信息

>>BRT(佰鸿工业)